Driving decarbonization and digitalization. Together.



Staff Engineer Package Concept Engineering (f/m /div)

Job description

As Staff Engineer Package Concept Engineering you will be the first contact point for all backend related topics during the early product lifecycle. Beginning with first customer requirements you align with our technical marketing on product development strategies. With a multi-layered view on technical complex subjects and package knowhow you can implement your own ideas and solutions. The best part: You can drive innovation and see the results! While setting up collaboration between frontend /backend and product development teams you will be able to get a wide spread knowledge in packaging technology. As you continually expand both your expert knowledge and network to solve problems, you will position yourself as a communication hub - establishing the connection between package innovation, package manufacturing and product definition until its realization.

In your new role you will:

- Examine new package concepts by considering alternatives and leverage synergies to other divisions and package development sites
- Coordinate complex package development projects in a global and interdisciplinary environment
- Be the go-to person for all backend relevant topics; therefore, you will c ollaborate closely with Application Engineering, Marketing, Product Development and Package
- Create and support innovative ideas in power electronic and IC packaging; therefore, you are aware of relevant trends regarding packaging
- Create package roadmaps for i ndividual product groups in collaboration with application engineering, marketing and backend innovation
- Collaborate with Technical/Product Marketing to foresee future trends: prepare package technologies by triggering innovation projects and prototypes
- Actively drive problem solving processes in the area of chip/package interplay

At a glance

Location:

Job ID: HRC0748492
Start date: Jun 01, 2024
Entry level: 3-5 years
Type: Full time
Contract: Permanent

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Job ID: HRC0748492

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Contact

Bárbara Moreira

Profile

You are open to new ideas and receptive to other ways of thinking or working. Furthermore, you remain focused on solutions, open, and flexible even when under pressure. Lastly, you are able to quickly establish a successful cooperation.

You are best equipped for this task if you have:



- A degree in Electrical Engineering, Physics, Mechanical Engineering or a related field
- 3-5 years of relevant work experience with focus on packaging of semiconductor products
- Good understanding of application requirements regarding packaging concepts, characteristics, and related failure mechanisms
- Experience with CAD would be a big plus
- Excellent stakeholder management skills to handle your internal and external global interfaces with your intercultural competencies
- Fluent English and German skills in verbal and written communication

Benefits

Munich:

Why Us

Driving decarbonization and digitalization. Together.

Infineon designs, develops, manufactures, and markets a broad range of semiconductors and semiconductor-based solutions, focusing on key markets in the automotive, industrial, and consumer sectors. Its products range from standard components to special components for digital, analog, and mixed-signal applications to customer-specific solutions together with the appropriate software.

- Green Industrial Power (GIP) empowers a world of unlimited green energy -

The GIP division delivers leading semiconductor solutions for the smart, green, and efficient conversion of electrical energy, covering all steps in the energy chain from generation through transmission to storage and consumption. Its broad range of applications spans renewable energies, electric vehicle charging, industrial power supplies, trains, electric commercial vehicles, and home appliances.

The GIP product portfolio encompasses IGBT power transistors and the driver ICs that control them, flanked by an expanding lineup of solutions based on SiC. Its growing analytics, service, and software offering complements this wide spectrum – reaching beyond products to create additional value for customers. Infineon is the global number one in power semiconductors and – with the broadest portfolio of SiC solutions for industrial applications – GIP is leading the transition to wide-bandgap technologies. GIP solutions handle energy more intelligently and efficiently – driving decarbonization for a better tomorrow.

Click here for more information about working at GIP with interesting employee and management insights and an overview with more #GIPDreamJobs.

We are on a journey to create the best Infineon for everyone.

This means we embrace diversity and inclusion and welcome everyone for who they are. At Infineon, we offer a working environment characterized by trust, openness, respect and tolerance and are committed to give all applicants and employees equal opportunities. We base our recruiting decisions on the applicant´s experience and

We look forward to receiving your resume, even if you do not entirely meet all the requirements of the job posting.

Please let your recruiter know if they need to pay special attention to something in order to enable your participation in the interview process.

Click here for more information about Diversity & Inclusion at Infineon.

